

SYSTEM AND METHOD FOR INSPECTING A WAFER

Abstract

A method and a system for inspecting a wafer. The system comprises an optical inspection head, a wafer table, a wafer stack, a XY table and vibration isolators. The optical inspection head comprises a number of illuminators, image capture devices, objective lens and other optical components. The system and method enables capture of brightfield images, darkfield images, 3D profile images and review images. Captured images are converted into image signals and transmitted to a programmable controller for processing. Inspection is performed while the wafer is in motion. Captured images are compared with reference images for detecting defects on the wafer. An exemplary reference creation process for creating reference images and an exemplary image inspection process is also provided by the present invention. The reference image creation process is an automated process.

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Figure 1